Electronic Patent Application Fee Transmittal							
Application Number:	105	10590210					
Filing Date:	22-	22-Aug-2006					
Title of Invention:	Me	Method of molding for microneedle arrays					
First Named Inventor/Applicant Name:	Ma	Mary R. Boone					
Filer:	Chi	Christopher Michael Geise./Rebecca Bode					
Attorney Docket Number:	594	59404US004					
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Filing	Fee	5					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:					1		
Notice of appeal		1401	1	540	540		
Post-Allowance-and-Post-Issuance:							
Extension of Times							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			540